

Title (en)
ENCAPSULATION, MEMS AND ENCAPSULATION METHOD

Title (de)
VERKAPSELUNG, MEMS SOWIE VERFAHREN ZUM VERKAPSELN

Title (fr)
ENCAPSULAGE, SYSTÈME MICRO-ÉLECTROMÉCANIQUE ET PROCÉDÉ D'ENCAPSULAGE

Publication
EP 2326592 A2 20110601 (DE)

Application
EP 09780584 A 20090715

Priority
• EP 2009059009 W 20090715
• DE 102008042106 A 20080915

Abstract (en)
[origin: WO2010028884A2] The invention relates to the encapsulation (4) of a sensitive mechanical component structure (3) on a semiconductor substrate (2) by means of a film (5) that covers the component structure (3) and has at least one polymer layer (8). At least one cavity (7) is provided between the component structure (3) and the film (5). According to the invention, the film (5) is penetrated by at least one via (15).

IPC 8 full level
B81C 1/00 (2006.01)

CPC (source: EP US)
B81B 7/0041 (2013.01 - EP US); **H01L 24/02** (2013.01 - US); **B81B 2207/095** (2013.01 - EP US); **B81C 2203/0109** (2013.01 - EP US); **B81C 2203/019** (2013.01 - EP US); **H01L 2224/0401** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01028** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/0105** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/014** (2013.01 - EP US); **H01L 2924/1461** (2013.01 - EP US)

Citation (search report)
See references of WO 2010028884A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)
AL BA RS

DOCDB simple family (publication)
DE 102008042106 A1 20100318; EP 2326592 A2 20110601; TW 201018640 A 20100516; US 2011180887 A1 20110728; US 8680665 B2 20140325; WO 2010028884 A2 20100318; WO 2010028884 A3 20101223

DOCDB simple family (application)
DE 102008042106 A 20080915; EP 09780584 A 20090715; EP 2009059009 W 20090715; TW 98130861 A 20090914; US 200913063722 A 20090715